



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN APG-CRM/06/2223
Notification Date 12/21/2006

BOM (Bill of Material) CHANGE ON LQFP 20x20 IN ASE CHUNG-LI

CRM - CAR RADIO & MULTIMEDIA DIV

Table 1. Change Identification

Product Identification (Product Family/Commercial Product)	E-TDA7590 & E-TDA7590TR
Type of change	Package assembly material change
Reason for change	Frame & New material set to be compliant to Jedec 020C qualification
Description of the change	Frame change from Ase material to Possehl double Ag ring plating and new assy material to be compliant to 260 C reflow temperature
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	No marking change - Internal traceability
Manufacturing Location(s)	1]Ase Chung Li

Table 2. Change Implementation Schedule

Forecasted implementation date for change	15-Feb-2007
Forecasted availability date of samples for customer	19-Dec-2006
Forecasted date for STMicroelectronics change Qualification Plan results availability	30-Jan-2007
Estimated date of changed product first shipment	28-Feb-2007

Table 3. Change Responsibility

	Name	Signature	Date
Division Product Manager	R. CARENA		Dec.19 ,06
Division Q.A. Manager	L. MERCANDELLI		Dec.19 ,06
Division Marketing Manager	A. RADAELLI		Dec.19 ,06

Table 4. List of Attachments

Customer Part numbers list	
Qualification Plan results	

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Customer Acknowledgement of Receipt		PCN APG-CRM/06/2223
Please sign and return to STMicroelectronics Sales Office		Notification Date 12/21/2006
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	Name:	
	Title:	
	Company:	
	Date:	
	Signature:	
Remark		



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WHAT:

Following ASE Chung-li request to find a second source for the frames of LQFP 20x20, we have taken the occasion of the leadframe qualification to upgrade the assy materials to be compliant to the Jedec 020C spec for leadfree production and achieve the 260° C reflow peak body temperature.

The frame design remains unchanged. Frame differencies are:

From Ase material Full Ag Spot plating to Possehl frames supplier Double Ag Ring plating.

Material change:

Glue die attach from Ablestik 8340 to Hitachi EN4900G

Molding compound from Hitachi CEL 9220T to Hitachi 9240

WHY:

To achieve 260° C reflow peak body temperature and be compliant to Jedec 020C spec.

HOW:

Here following is the qualification plan we are following to qualify the changes:

T.V. V356 E-TDA7590

- JL3@260degC + 1000 TC (-50/+150degC), s/s 77pcs x 3 assy lots
- JL3@260degC + PPT (2atm, 121degC, 168h), s/s 77pcs x 3 assy lots
- JL3@260degC + THB (85degC, 85% RH, 1000h), s/s 23pcs x 3 assy lots
- HTS (Ta=150degC, 1000h), s/s 45pcs x 3 assy lots

End of the qualification is forecasted for end January 07.

WHEN:

Asap upon customer's agreement.

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